



Material Content Data Sheet



Sales Product Name		BTS3405G		Issued		2. August 2018		
MA#		MA001055002						
Package		PG-DSO-8-25		Weight*		83.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.434	1.72	1.72	17238	17238
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8623	
wire	non noble metal	copper	7440-50-8	29.121	35.01	35.92	350110	359272
	noble metal	gold	7440-57-5	0.357	0.43	0.43	4287	4287
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1185
encapsulation	plastics	epoxy resin	-	4.534	5.45		54507	
	inorganic material	silicondioxide	60676-86-0	44.647	53.69	59.26	536774	592466
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9784	9784
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7818	7818
glue	plastics	epoxy resin	-	0.133	0.16		1599	
	noble metal	silver	7440-22-4	0.627	0.75	0.91	7536	9135
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com